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Jpw**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Appl. Serial No. : 09/720,761 Confirmation No. 5642

Title : METHOD OF PLASMA ETCHING OF SILICON

Applicant(s) : Franz LAERMER et al.

Filed : March 26, 2001

TC/A.U. : 1765

Examiner : Kin Chan Chen

Docket No. : 10191/1629 hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail

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Date: 5/13/2004

Signature: AARON C. DEDITCH  
(33,865)

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ONLY**TRANSMITTAL OF REPLACEMENT AMENDMENT**

SIR:

Transmitted herewith for filing in the above-identified patent application is a Replacement Amendment for the Amendment filed March 31, 2004 (and mailed on March 29, 2004).

While no fee is believed to be due (since this Replacement Amendment is being filed within one month of the Notice of Non-Compliant Amendment mailed on April 13, 2004), the Commissioner is authorized to charge payment of any fees (including any extension fees) associated with this communication or credit any overpayment to the deposit account of Kenyon & Kenyon, deposit account number 11-0600. A duplicate copy of this page is enclosed.

Respectfully submitted,

By: Richard L. MayerRichard L. Mayer  
(Reg. No. 22,490)Dated: 5/13/2004

KENYON & KENYON  
One Broadway  
New York, New York 10004  
(212) 425-7200

33,865  
Aaron C.  
(33,865)

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